

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3,5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	2.80mil	4,8	
5	GND1	Copper	1.40mil		
6	Dielectric 3	FR-4	19.00mil	4,2	
7	GND2	Copper	1.40mil		
8	Dielectric 2	FR-4	2.80mil	4,2	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3,5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
 MIN. CLEARANCE: 0.2 mm
 MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
 HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER _____
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER 31 mil
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES
 PTH COPPER THICKNESS: 20-30 um OTHER _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR: GREEN OTHER _____
 MATTE SEMI-GLOSS

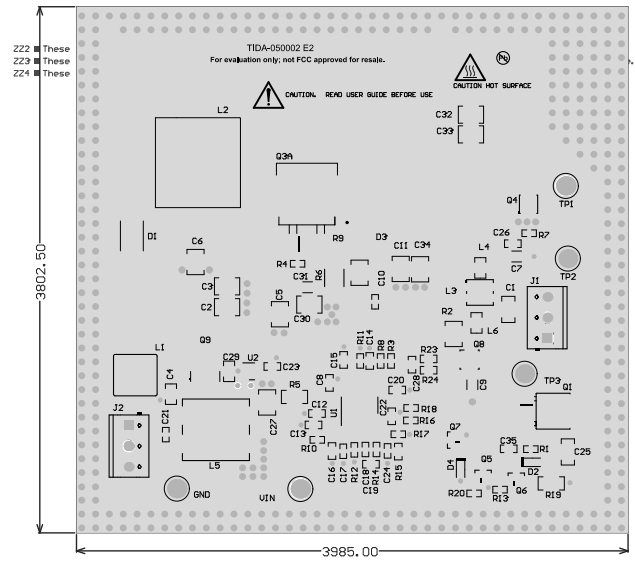
SURFACE FINISH: IMMERSION GOLD (ENIG) ENIG
 IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER M1 BOARD OUTLINE
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 RoHS OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94V-0 REQUIREMENTS.
 PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER



COMPONENTS MARKED 'DNP' SHOULD NOT BE ORDERED. TO ORDER, REMOVE 'DNP' FROM THE PART NUMBER.
 ASSEMBLY VARIANT: [No Variants]

REV	DATE	DESCRIPTION	BY	CHKD	APP'D
1	10/25/2010	Initial Release	Tuan Tran	John Bump	

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ENGINEER:	LAYOUT BY:
Tuan Tran	John Bump
SCALE: 1.00	ALTIUM DESIGNER VERSION:
	17.1.9.592

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